

Cypress Semiconductor Qualification Report

**QTP# 97383 VERSION 1.0
January, 1998**

**32 Ld SOJ Package - Hitachi CEL9200 Mold Compound
Omedata, Indonesia Assembly**

PLASTIC PACKAGE/ASSEMBLY DESCRIPTION			
Package Outline, Type, or Name:	32 Ld SOJ		
Mold Compound Name/Manufacturer:	Hitachi CEL9200		
Lead Frame material:	Copper		
Lead Finish, composition:	Solder Plated, 85%Sn, 15%Pb		
Die Attach Area Plating:	Silver		
Die Attach Method:	Epoxy	Die Attach Material:	Ablestik 8361H
Wire Bond Method:	Thermosonic	Wire Material/Size:	Gold / 1.0 mil
JESD22-A112 Moisture Sensitivity Level	Level 1		
Assembly Line ID and Process ID:	Omedata, Indonesia (INDNS-O)		

Note: Please contact a Cypress Representative for other packages availability.

RELIABILITY TESTS PERFORMED

Stress/Test	Test Condition (Temp/Bias)	Result P/F
Temperature Cycle	MIL-STD-883C, Method 1010, Condition C, -65°C to 150°C Precondition: JESD22 Moisture Sensitivity Level 1 168 Hrs., 85°C/85%RH	P
High Accelerated Saturation Test	140°C/5.5V Precondition: JESD22 Moisture Sensitivity Level 1 168 Hrs., 85°C/85%RH	P
High Temperature Storage	165C, no bias	P
Resistance to Solvent	Cypress Spec 25-00016	P
X-Ray	Cypress Spec 12-000149	P
Acoustic Microscopy Test	Cypress Spec 25-00104	P

RELIABILITY TEST DATA

QTP#: 97383

DEVICE	ASSY-LOC	FABLOT#	ASSYLOT#	DURATION	S/S	REJ	FAIL MODE
STRESS: HI-ACCEL SATURATION TEST (140C, 5.5V), PRECOND. 168 HRS 85C/85%RH							
CY7C109-VC	INDNS-O	4722615	519708179	128	49	0	
STRESS: HIGH TEMPERATURE STORAGE (165C, NO BIAS)							
CY7C109-VC	INDNS-O	4722615	519708179	336	49	0	
CY7C109-VC	INDNS-O	4722615	519708179	500	48	0	
CY7C109-VC	INDNS-O	4722615	519708179	1000	48	0	
STRESS: TC COND. C, -65 TO 150C, PRECOND. 168 HRS 85C/85%RH							
CY7C109-VC	INDNS-O	4722615	519708179	300	49	0	
CY7C109-VC	INDNS-O	4722615	519708179	1000	49	0	
CY7C107-VC	INDNS-O	4722615	519708413	300	48	0	
CY7C107-VC	INDNS-O	4722615	519708413	1000	48	0	
CY7C106-VC	INDNS-O	4722615	519708434	300	48	0	
CY7C106-VC	INDNS-O	4722615	519708434	1000	48	0	